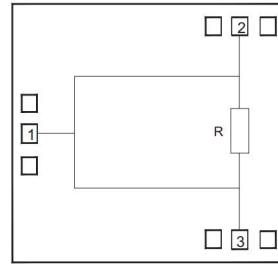


Performance

- Frequency: 1~18GHz
- Insertion loss: 1.8dB
- Chip size: 2.60*2.20*0.1mm

Function Diagram

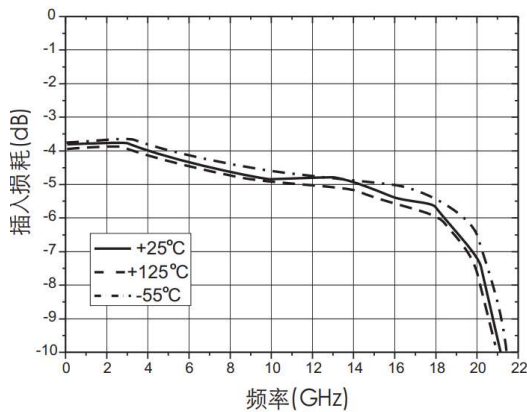


Electrical Specifications (Ta=+25°C, 50Ω system)

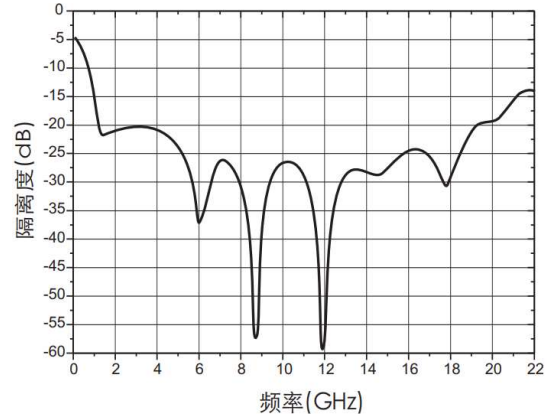
Parameter		Min	Typical	Max	Unit
Frequency Range		1~18			GHz
Insertion Loss	1~10GHz	-	1.2	1.8	dB
	10~18GHz	-	2.2	2.7	
Insertion Loss Ripple		-	±1	-	dB
Isolation		15	22	-	dB
Input Return Loss		12	20	-	dB
Output Return Loss		13	20	-	dB

Test Curves

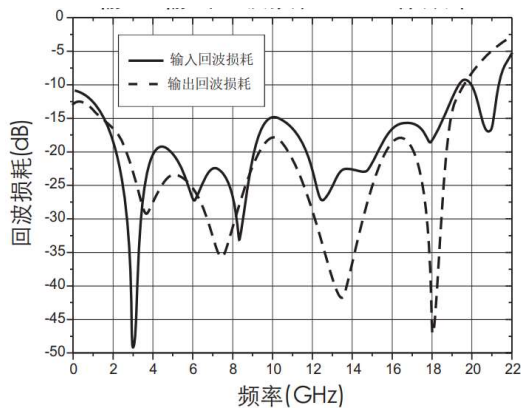
Insertion loss vs. Freq



Isolation vs. Freq



Input/Output Return Loss vs. Freq



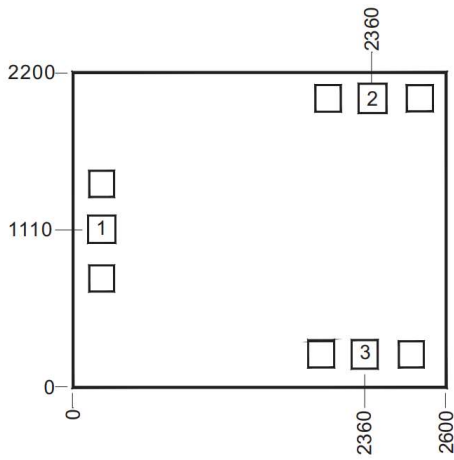
Absolute Max Ratings

RF Input Power	+37dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Junction Temperature	175°C
Static Protection (HBM)	Class 1A



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

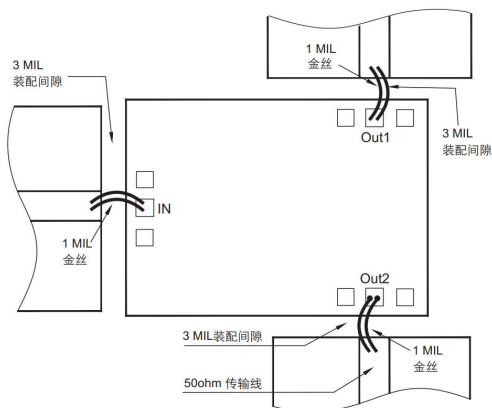
Outline Size



Note:

1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: $100 \times 100 \mu\text{m}$
5. Don't bonding on thru holds
6. Tolerance: $\pm 50 \mu\text{m}$

Assembly Diagram



Bonding Definition

No.	Symbol	Description
1	In	RF Input, 50ohm
2, 3	Out1, Out2	RF Output, 50ohm
	GND	Bottom must be grounded